

Silicon Epitaxial Planar Switching Diode

Features

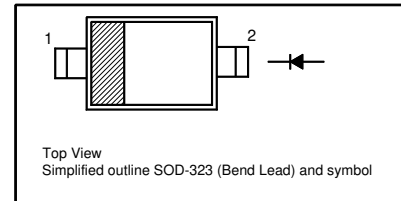
- AEC-Q101 Qualified
- SOD-323(Bend Lead) package
- Fast switching
- These diodes are also available in other case style including the DO-35 case with the type designation 1N4148, the MiniMELF case with the type designation LL4148 and the MicroMELF case with the type designation MCL4148.
- Halogen and Antimony Free(HAF), RoHS compliant

Applications

- High-speed switching
- General-purpose switching

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	75	V
Average Rectified Forward Current	$I_{F(AV)}$	150	mA
Surge Forward Current	I_{FSM}	2 1	A
Power Dissipation	P_{tot}	200	mW
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	625	$^\circ\text{C/W}$

¹⁾ Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 1 \mu\text{A}$	$V_{(BR)R}$	75	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	V_F	- - - -	0.715 0.855 1 1.25	V
Peak Reverse Current at $V_R = 75 \text{ V}$ at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}, T_J = 150^\circ\text{C}$ at $V_R = 25 \text{ V}, T_J = 150^\circ\text{C}$	I_R	- - - -	1 25 50 30	μA nA μA μA
Total Capacitance at $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_T	-	2	pF
Reverse Recovery Time at $I_{rr} = 0.1 \times I_R, I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 100 \Omega$	t_{rr}	-	4	ns

Electrical Characteristics Curves

Fig 1. Power Derating Curve

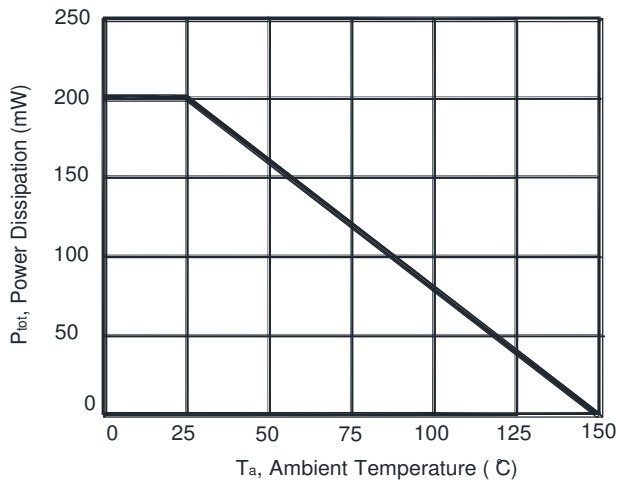


Fig 2. Total Capacitance vs. Reverse Voltage

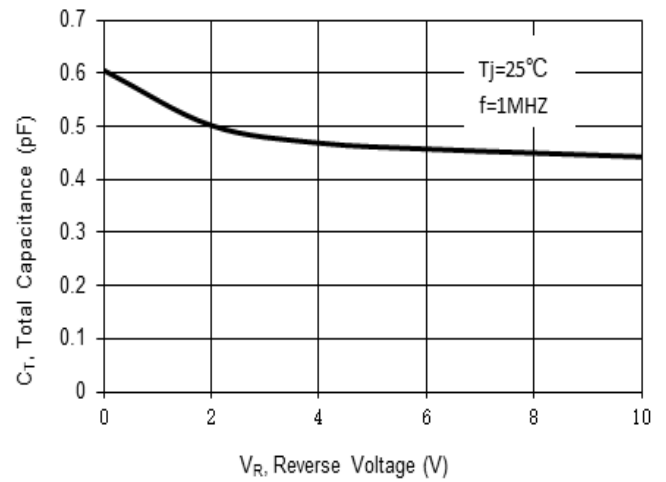


Fig 3. Reverse Current vs. Reverse Voltage

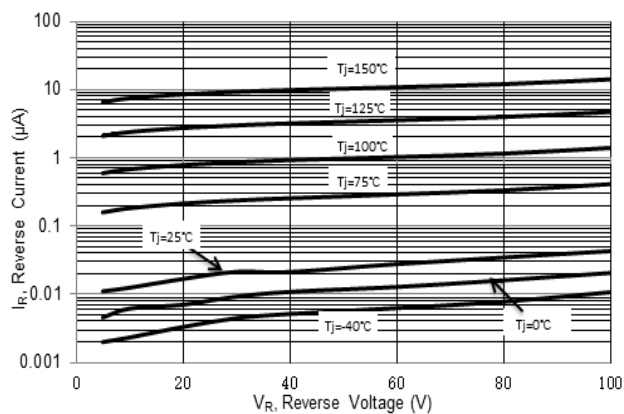
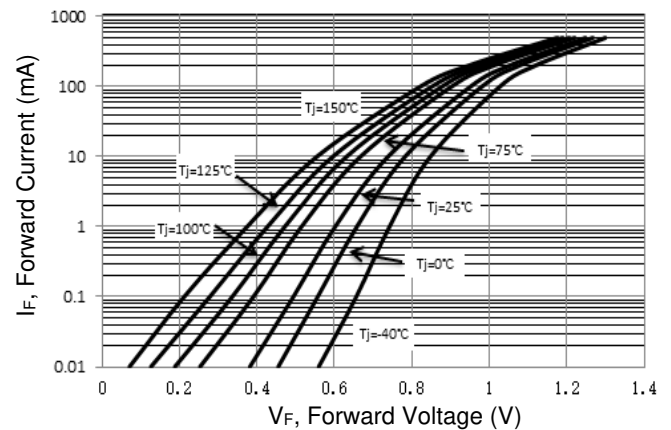


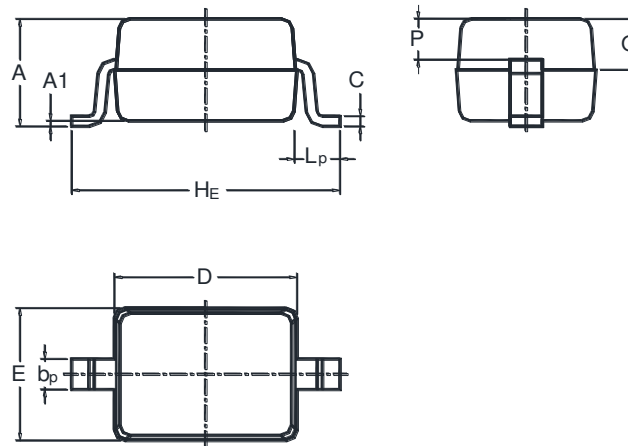
Fig 4. Forward Characteristics



PACKAGE OUTLINE

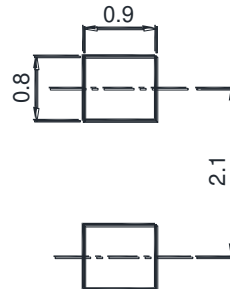
Plastic surface mounted package; 2 leads

SOD-323(Bend Lead)



UNIT	A	A ₁	b _P	C	D	E	H _E	L _P	Q	P
mm	1.1 0.8	0.1 0	0.4 0.25	0.18 0.09	1.8 1.6	1.35 1.15	2.8 2.3	0.5 0.1	0.5 0.3	0.4 0.3

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOD-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" W2 " = Part No.

" III " = Cathode line

" • " = HAF (Halogen and Antimony Free)

Font type: Arial

